

FlipChip International Introduces *EliteCSP™* Wafer Level Package and License with Fraunhofer Institute for Advanced Low Cost Wafer Bumping.

PHOENIX, ARIZONA April. 26, 2005--FlipChip International today announced the introduction of its new *EliteCSP™* product for wafer level packaging and wafer bumping. The *EliteCSP™* product line is specifically designed for bumping applications that require rapid cycle times, quick time to market, low bumping costs, and high temperature stability. This technology was developed primarily at FlipChip International and was supported by a global licensing agreement with the Fraunhofer Institute (IZM) in Berlin, Germany for the electroless plating of the underbump metallization (UBM). The Fraunhofer license solidifies and strengthens internally developed and patented electroless plating technologies for nickel/palladium/gold already in place at FlipChip International.

As part of the *EliteCSP™* product introduction, FlipChip International has installed high volume plating capabilities in its Phoenix bumping facility. This technology offers FlipChip International's customers a low cost alternative to its thin film sputtered metallization and is complimentary to its diverse solder bumping technologies.

The electroless plating equipment for the *EliteCSP™* process is fully automated and has the capacity to process over 200,000 wafers annually. The process is designed for semiconductor devices with both aluminum and copper based pad structures. A wide variety of wafer materials can be processed with this technology, including: silicon, gallium arsenide, sapphire, and quartz. The facility contains a full set of supporting equipment and analytical tools to ensure a robust and flexible process.

Bob Forcier, President and CEO of FlipChip International, said, "We are very pleased to expand our technology offering to include our new *EliteCSP™* product series. The implementation of this process will enable FCI to enter into several new wafer bumping markets where the technology has proven reliable and cost effectiveness, including: RFID devices, smart cards, solid state lighting, passive components, and power devices. Together with our existing wafer bumping and assembly operations, it truly makes FlipChip International a full service provider in the flip chip packaging arena."

Dr. Haluk Balkan, Vice President of Engineering, added, "We are excited about the addition of the *EliteCSP™* offerings to our current wafer bumping processes. This extends our wafer bumping technology to what we believe will be a low cost enabler to more customers. In addition to the low cost markets, we believe this technology will quickly lend itself to the higher end devices, where 300mm wafer sizes, copper pads, high speeds, and high density are performance based requirements."

Fraunhofer is the largest organization for applied research and development in Germany, comprising over 60 institutes. Fraunhofer IZM is one of the world's leading institutes for advanced packaging and interconnect technologies.

FlipChip International, LLC is a privately-held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. Flip Chip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets.

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